

# **Unlock the NoC: Transforming NoC Research with Physical Design Awareness**

Christopher Batten (Cornell University)  
Michael Taylor (University of Washington)

NOCS'20 Special Session



## **Christopher Batten**

Associate Professor, Cornell University

Computer Architecture, EDA, VLSI

Tapeouts in 180/130/28/16nm

Early work on nanophotonic chip-level interconnection networks



## **Michael Taylor**

Associate Professor, University of Washington

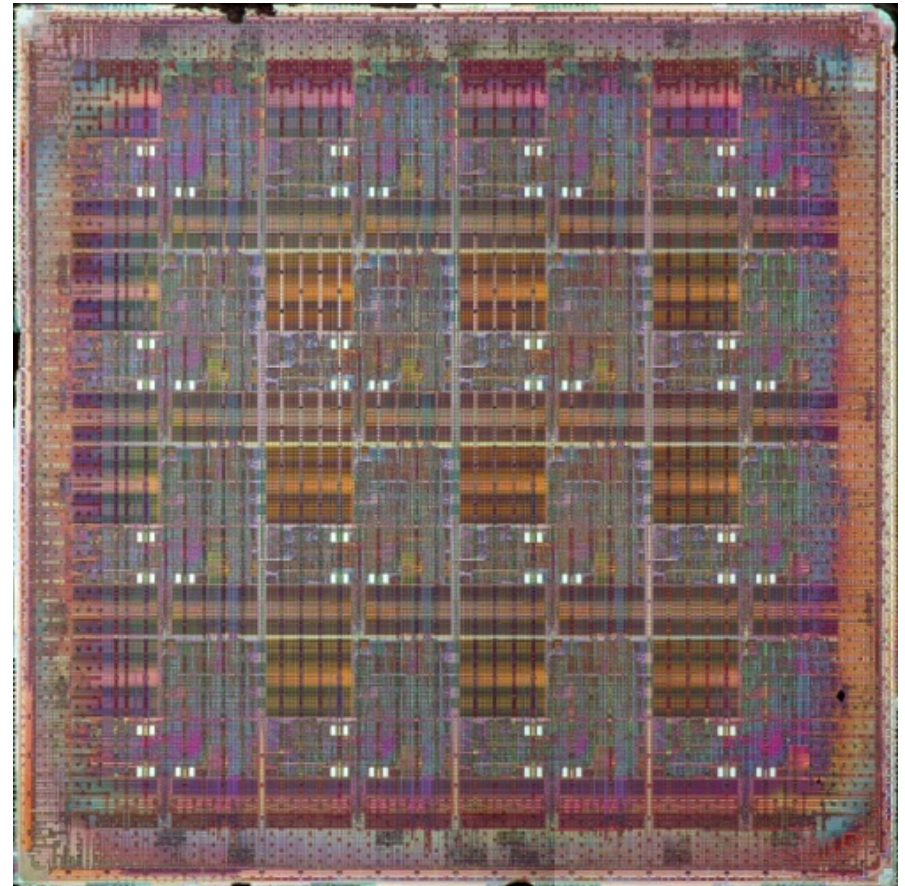
Computer Architecture, VLSI

Tapeouts in 180/40/28/16/12nm

Pioneered scalar-operand networks, one of the first academic works on NOCs

## MIT RAW Processor [IEEE-Micro'02,ISSCC'03]

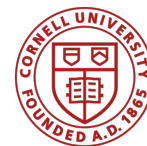
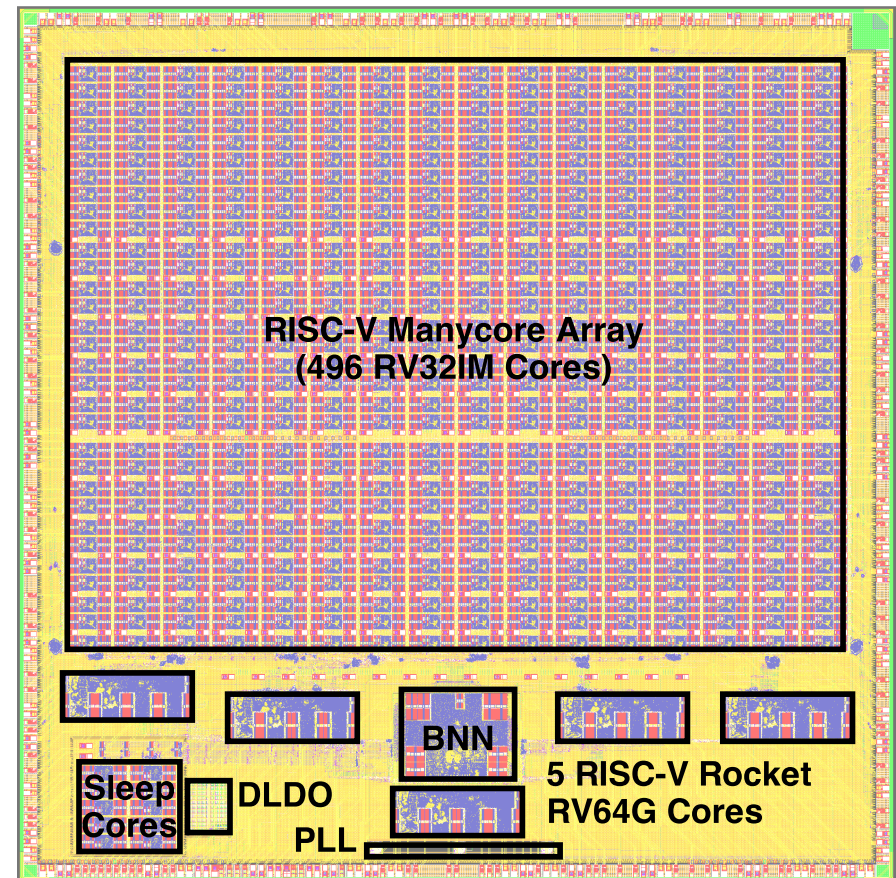
- ▶ 18 × 18mm in IBM 180 nm
- ▶ 16 MIPS-like cores
- ▶ 4 × 4 mesh network-on-chip
  - ▷ 2 statically configured NoCs for scalar operands
  - ▷ 2 dynamically routed Nocs for memory traffic
  - ▷ XY dimension ordered routing
  - ▷ Four physical networks, no VCs





# Celerity System-on-Chip [IEEE-Micro'18, VLSI'19]

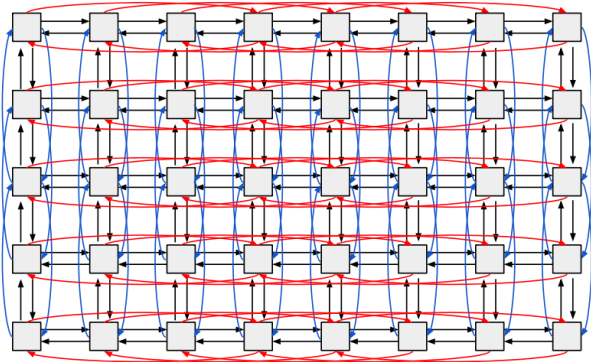
- ▶ 5 × 5mm in TSMC 16 nm FFC
- ▶ 385 million transistors
- ▶ 511 RISC-V cores
  - ▷ 5 Linux-capable Rocket cores
  - ▷ 496-core tiled manycore
  - ▷ 10-core low-voltage array
- ▶ 1 BNN accelerator
- ▶ 1 synthesizable PLL
- ▶ 1 synthesizable LDO Vreg
- ▶ 3 clock domains
- ▶ **16×31 mesh network-on-chip**
  - ▷ Remote-store programming
  - ▷ One-cycle router+channel latency
  - ▷ XY dimension ordered routing
  - ▷ One physical network, no VCs



# Physical Design Issues

---

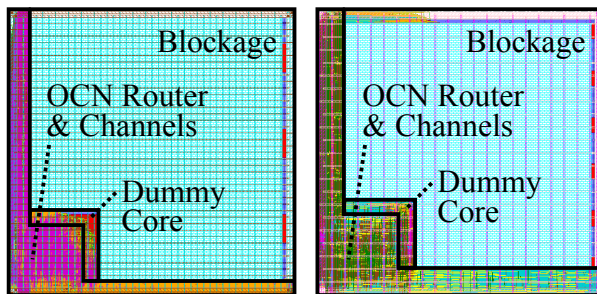
- ▶ **Timing Closure:** Must meet both min and max timing constraints across entire chip and multiple corners
- ▶ **Silicon Utilization:** Must effectively use both active area and wiring resources without negatively impacting other design issues
- ▶ **Power Distribution:** Must ensure no static IR drop nor  $di/dt$  voltage noise issues; carefully balance power grid vs signal routing resources
- ▶ **Hierarchical Design:** Carefully consider hard macros which can address some physical design issues while at the same time creating new challenges
- ▶ **EDA Tool Runtime:** Must facilitate an agile chip design methodology where we can spin an entire chip in less than a day
- ▶ **Signal Integrity:** Global signals must always operate robustly even in the context of voltage noise and aggressor signals
- ▶ **Custom Circuits:** Carefully consider the impact of mixing custom and standard-cell-based design methodologies



► **Ruche Networks:**

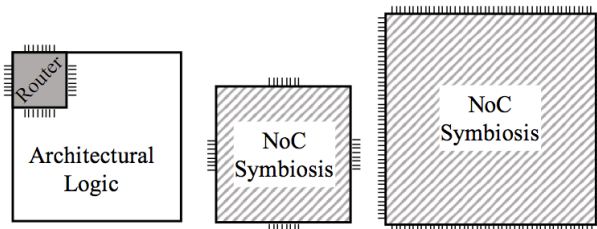
**Wire-Maximal, No-Fuss NoCs**

*Dai Cheol Jung, Scott Davidson, Chun Zhao, Dustin Richmond, Michael Bedford Taylor (University of Washington)*



► **Implementing Low-Diameter On-Chip Networks Using a Tiled Physical Design Methodology**

*Yanghui Ou, Shady Agwa, Christopher Batten (Cornell University)*

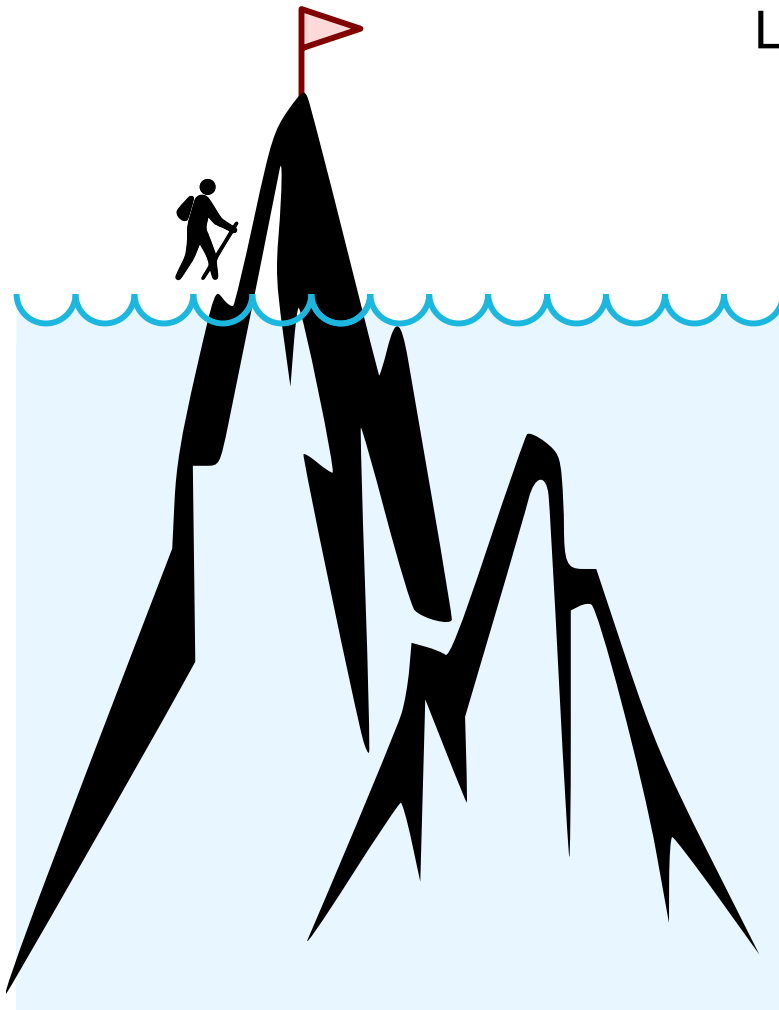


► **NoC Symbiosis**

*Daniel Petrisko, Chun Zhao, Scott Davidson, Paul Gao, Dustin Richmond, Michael Bedford Taylor (University of Washington)*

# Software Innovation Today

Like climbing an iceberg – much is hidden!



## Your proprietary code

- Instagram
- \$500K seed with 13 people → \$1B

## Open-source software

- Python
- Django
- Memcached
- Postgres/SQL
- Redis
- nginx
- Apache, Gnuicorn
- Linux
- GCC

"What Powers Instagram:  
Hundreds of Instances,  
Dozens of Technologies"  
<https://goo.gl/76fWrM>

Adapted from M. Taylor, "Open Source HW in 2030," Arch 2030 Workshop @ ISCA'16

# Hardware Innovation Today



Like climbing a mountain – nothing is hidden!

## What you have to build

- New machine learning accelerator
- Other unrelated components, anything you cannot afford to buy or for which COTS IP does not do

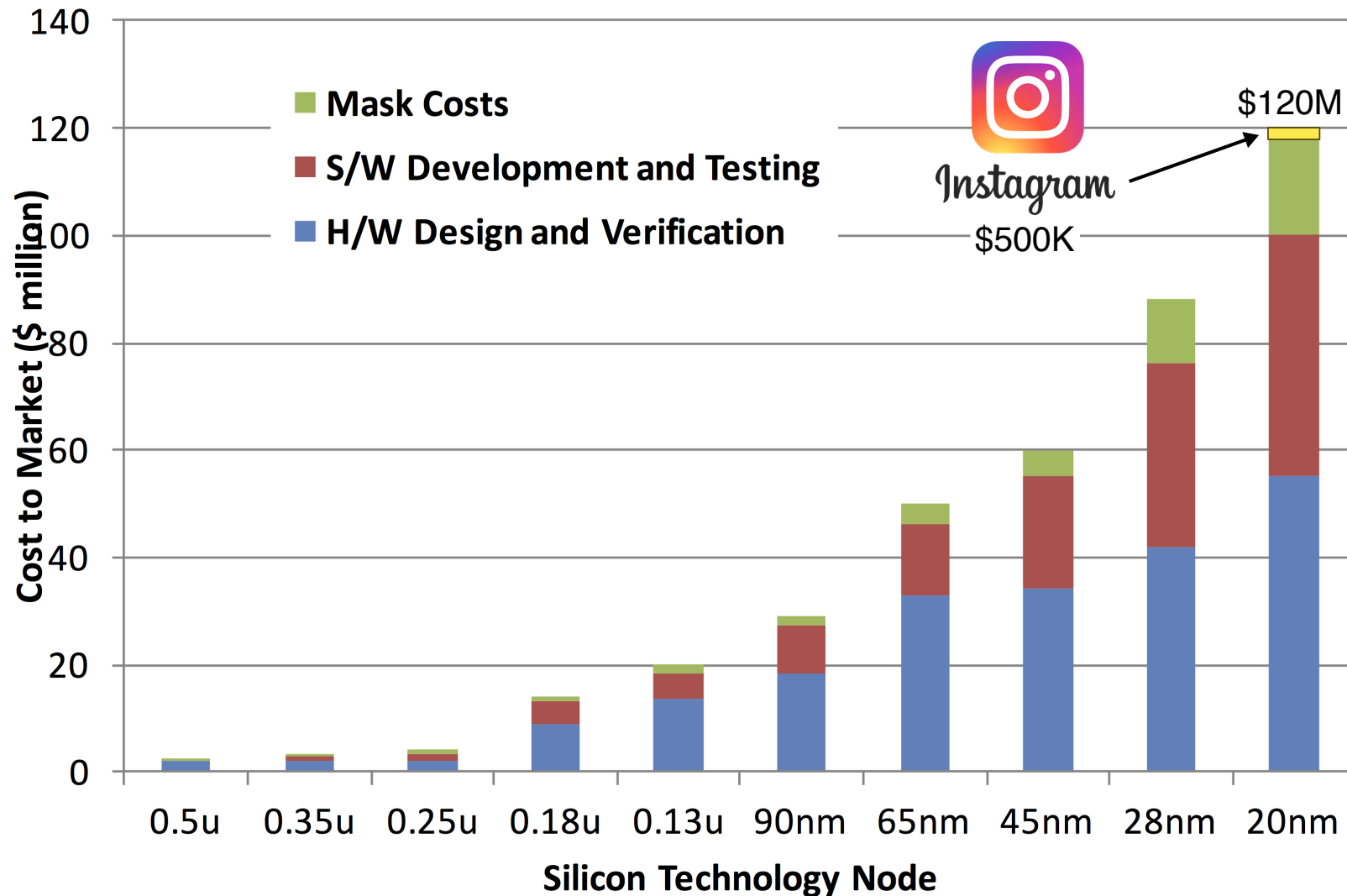
## Closed source

- ARM A57, A7, M4, M0
- ARM on-chip interconnect
- Standard cells, I/O pads, DDR Phy
- SRAM memory compilers
- VCS, Modelsim
- DC, ICC, Formality, Primetime
- Stratus, Innovus, Voltus
- Calibre DRC/RCX/LVS, SPICE

Adapted from M. Taylor, "Open Source HW in 2030," Arch 2030 Workshop @ ISCA'16



# Chip Costs Are Skyrocketing



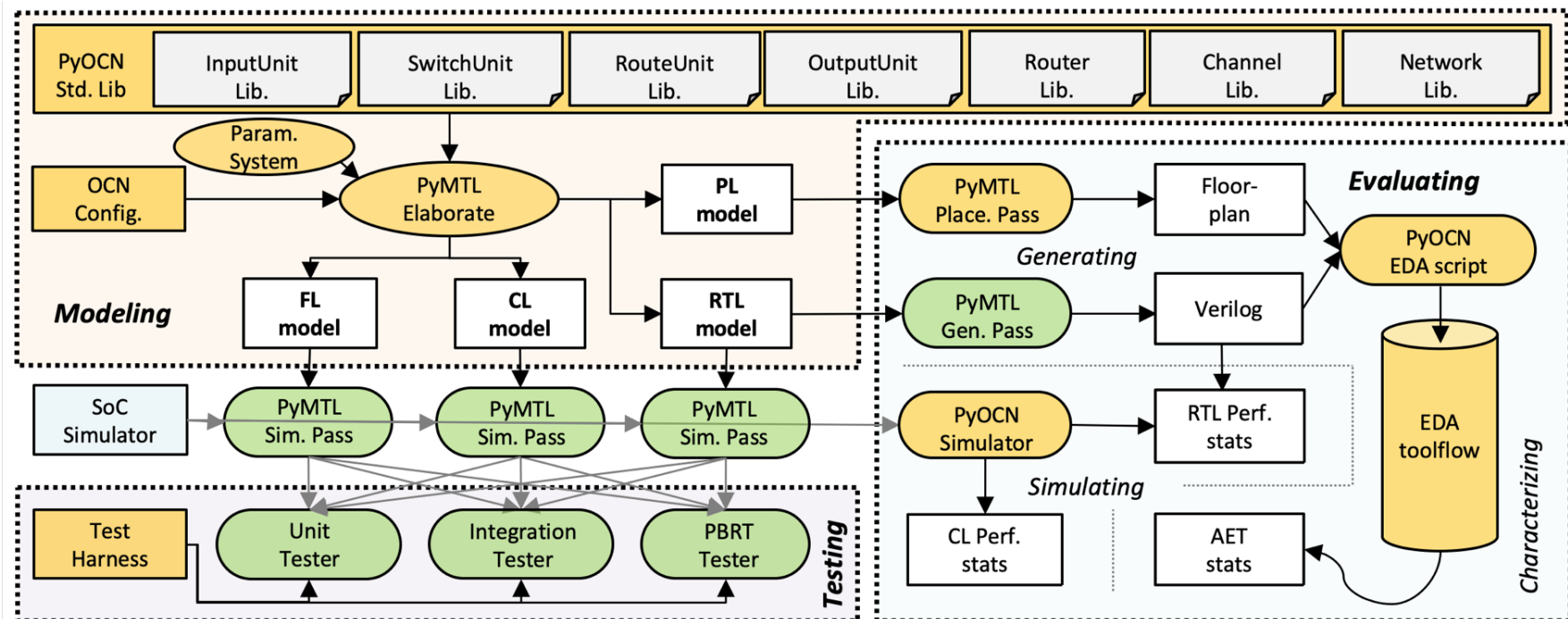
Adapted from M. Taylor, "Open Source HW in 2030," Arch 2030 Workshop @ ISCA'16; original: International Business Strategies & T. Austin.

# How can HW design be more like SW design?

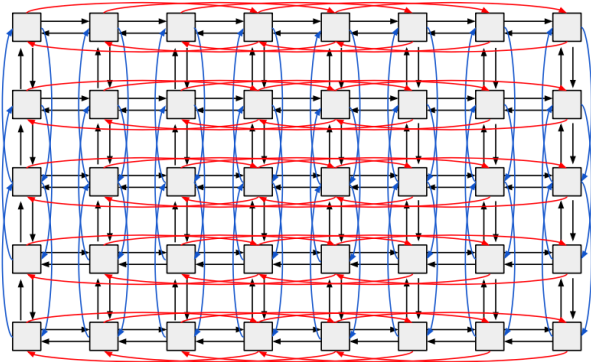
Open-Source	Software	Hardware
high-level languages	Python, Ruby, R, Javascript, Julia	Chisel, PyMTL, PyRTL, MyHDL, JHDL, Clash
libraries	C++ STL, Python std libs	<b>BaseJump, PyOCN</b>
systems	Linux, Apache, MySQL, memcached	Rocket, Pulp/Ariane, OpenPiton, Boom, FabScalar, MIAOW, Nyuzi
standards	POSIX	RISC-V ISA, RoCC, TileLink
tools	GCC, LLVM, CPython, MRI, PyPy, V8	Icarus Verilog, Verilator, qflow, Yosys, TimberWolf, qrouter, magic, klayout, ngspice
methodologies	agile software design	agile hardware design
cloud	IaaS, elastic computing	IaaS, elastic CAD

The screenshot shows the GitHub repository page for 'bespoke-silicon-group/basejump\_stl'. The repository has 17 watchers, 151 stars, and 37 forks. It contains 63 issues, 32 pull requests, and 1 tag. The file list includes folders like 'bsg\_async', 'bsg\_cache', 'bsg\_chip', 'bsg\_clk\_gen', 'bsg\_comm\_link', 'bsg\_dataflow', 'bsg\_dmc', 'bsg\_fpu', 'bsg\_mem', 'bsg\_mesosync\_io', 'bsg\_misc', 'bsg\_noc', 'bsg\_riscv', 'bsg\_tag', and 'bsg\_test'. The 'bsg\_noc' folder is circled in red. On the right side, the 'About' section is circled in red and contains the text: 'BaseJump STL: A Standard Template Library for SystemVerilog'. Below this, there are links for 'bjump.org', 'Readme', and 'View license'. The 'Releases' section shows 1 tag, and the 'Packages' section shows no packages published. The 'Contributors' section shows 22 contributors.

# PyOCN: A Unified Framework for Modeling, Testing, and Evaluating OCNs



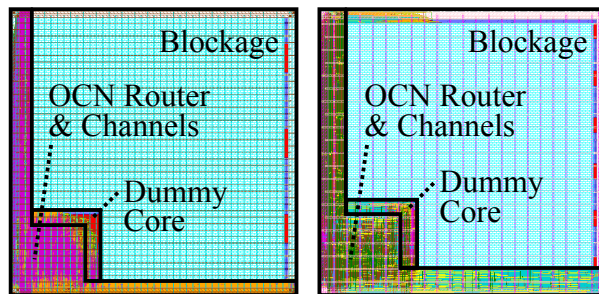
- ▶ Implemented using PyMTL3, a new Python modeling, generation, simulation, and verification framework [IEEE Micro'20, IEEE D&T '20]
- ▶ <https://github.com/pymtl/pymtl3-net>



► **Ruche Networks:**

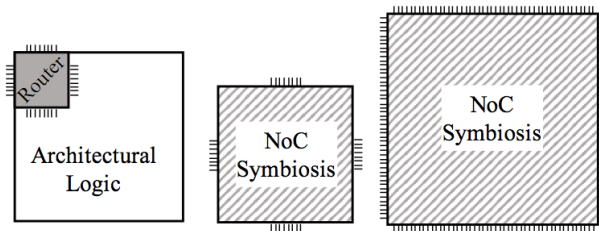
**Wire-Maximal, No-Fuss NoCs**

*Dai Cheol Jung, Scott Davidson, Chun Zhao, Dustin Richmond, Michael Bedford Taylor (University of Washington)*



► **Implementing Low-Diameter On-Chip Networks Using a Tiled Physical Design Methodology**

*Yanghui Ou, Shady Agwa, Christopher Batten (Cornell University)*



► **NoC Symbiosis**

*Daniel Petrisko, Chun Zhao, Scott Davidson, Paul Gao, Dustin Richmond, Michael Bedford Taylor (University of Washington)*